



N-Ch 80V Fast Switching MOSFETs

Description

The HSBL020N08 is the high cell density SGT N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous rectification applications.

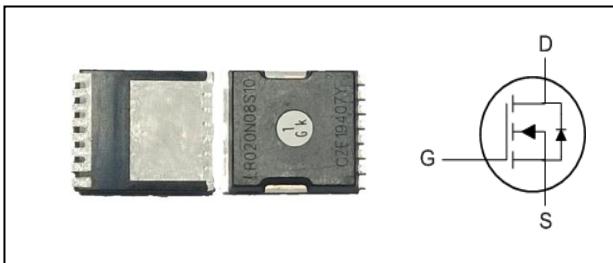
The HSBL020N08 meet the RoHS and Halogen-Free compliant product requirement, 100% EAS guaranteed with full function reliability approved.

Product Summary

V _{DS}	80	V
R _{DS(ON),typ}	1.4	mΩ
I _D	240	A

- 100% EAS Guaranteed
- Green Device Available
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

TOLL Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	80	V
V _{GS}	Gate-Source Voltage	±20	V
I _D @T _c =25°C	Continuous Drain Current, V _{GS} @ 10V ^{1,6}	240	A
I _D @T _c =100°C	Continuous Drain Current, V _{GS} @ 10V ^{1,6}	100	A
I _{DM}	Pulsed Drain Current ²	730	A
EAS	Single Pulse Avalanche Energy ³	2500	mJ
P _D @T _c =25°C	Total Power Dissipation ⁴	225	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-Ambient ¹	---	60	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	---	0.54	°C/W



Electrical Characteristics ($T_J=25^{\circ}\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_D=250\mu\text{A}$	80	---	---	V
$\text{R}_{\text{DS(ON)}}$	Static Drain-Source On-Resistance ²	$\text{V}_{\text{GS}}=10\text{V}$, $\text{I}_D=50\text{A}$	---	1.4	2.0	$\text{m}\Omega$
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}$, $\text{I}_D=250\mu\text{A}$	2	3	4	V
I_{DSS}	Drain-Source Leakage Current	$\text{V}_{\text{DS}}=80\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $\text{T}_J=25^{\circ}\text{C}$	---	---	1	uA
		$\text{V}_{\text{DS}}=80\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $\text{T}_J=125^{\circ}\text{C}$	---	---	5	
I_{GSS}	Gate-Source Leakage Current	$\text{V}_{\text{GS}}=\pm 20\text{V}$, $\text{V}_{\text{DS}}=0\text{V}$	---	---	± 100	nA
R_g	Gate Resistance	$\text{V}_{\text{DS}}=0\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	2	---	Ω
Q_g	Total Gate Charge (10V)	$\text{V}_{\text{DS}}=40\text{V}$, $\text{V}_{\text{GS}}=10\text{V}$, $\text{I}_D=50\text{A}$	---	204	---	nC
Q_{gs}	Gate-Source Charge		---	54	---	
Q_{gd}	Gate-Drain Charge		---	47	---	
$\text{T}_{\text{d(on)}}$	Turn-On Delay Time	$\text{V}_{\text{DD}}=40\text{V}$, $\text{V}_{\text{GS}}=10\text{V}$, $\text{R}_L=3\Omega$, $\text{I}_D=20\text{A}$	---	39	---	ns
T_r	Rise Time		---	136	---	
$\text{T}_{\text{d(off)}}$	Turn-Off Delay Time		---	121	---	
T_f	Fall Time		---	156	---	
C_{iss}	Input Capacitance	$\text{V}_{\text{DS}}=45\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	13650	---	pF
C_{oss}	Output Capacitance		---	20100	---	
Crss	Reverse Transfer Capacitance		---	580	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
V_{SD}	Diode Forward Voltage ²	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_s=50\text{A}$, $\text{T}_J=25^{\circ}\text{C}$	---	0.85	1.2	V
T_{rr}	Body Diode Reverse Recovery Time	$\text{I}_f=30\text{A}$, $\text{dI}/\text{dt}=500\text{A}/\text{us}$	---	112	---	ns
Q_{rr}	Body Diode Reverse Recovery charge	$\text{I}_f=30\text{A}$, $\text{dI}/\text{dt}=500\text{A}/\text{us}$	---	313	---	nC

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The power dissipation is limited by 150°C junction temperature
- 4.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.
- 5.The maximum current rating is package limited.



Typical Characteristics

Figure 1. Typ. Output Characteristics ($T_j=25^\circ\text{C}$)

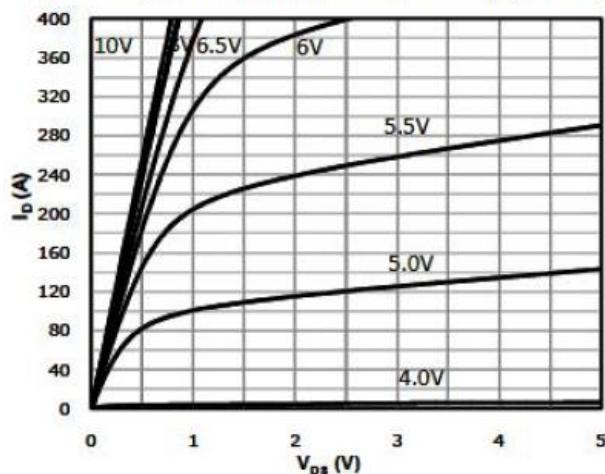


Figure 3. On-Resistance vs. Drain Current Junction and Gate Voltage Figure

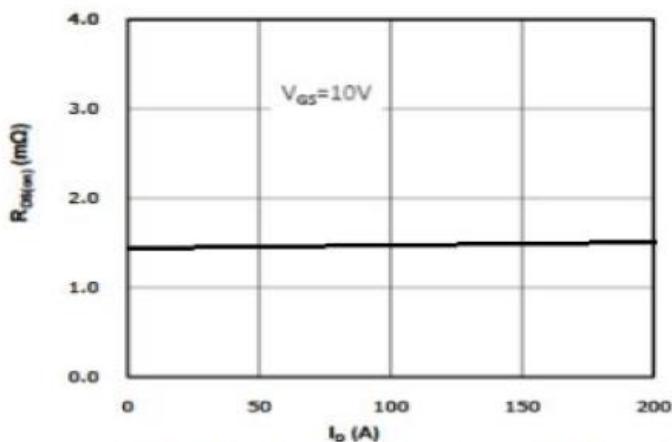
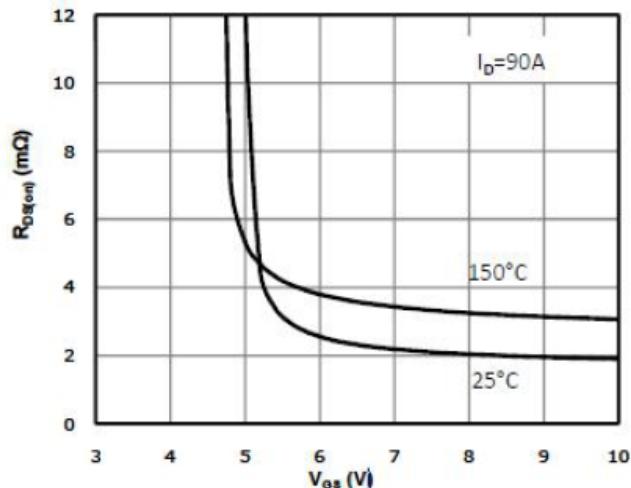


Figure 5. On-Resistance vs. Gate-Source Voltage (Junction Temperature)

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N-Ch 80V Fast Switching MOSFETs

Figure 2. Transfer Characteristics (Junction Temperature)

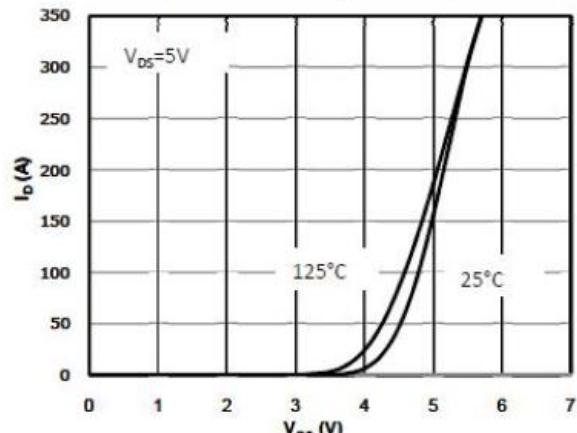


Figure 4. On-Resistance vs. Temperature

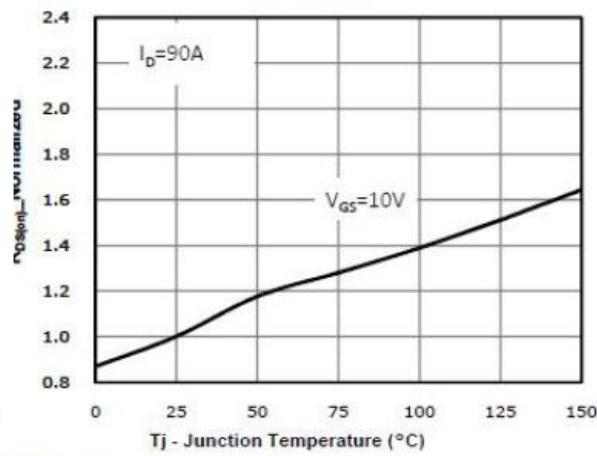


Figure 6. Body-Diode Characteristics (Junction Temperature)

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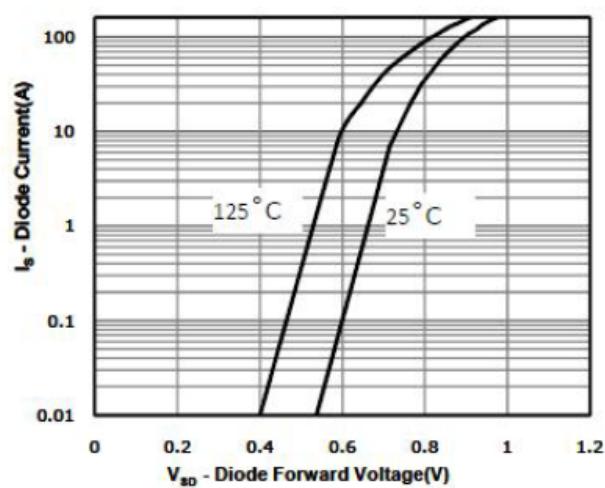
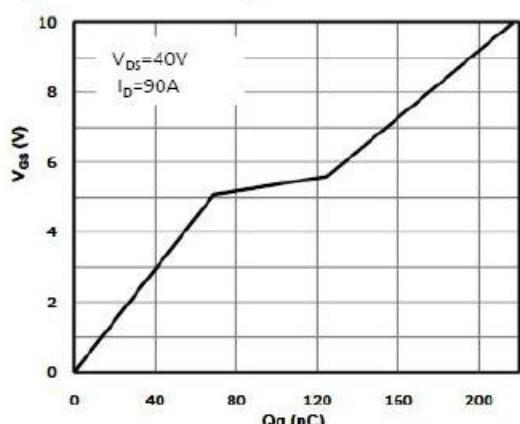




Figure 7. Gate-Charge Characteristics



N-Ch 80V Fast Switching MOSFETs

Figure 8. Drain Current Derating

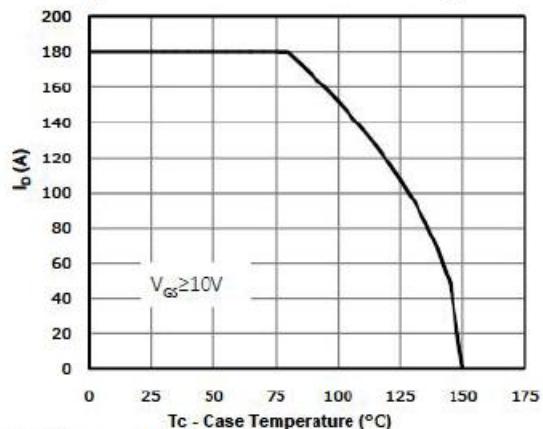


Figure 9. Capacitance Characteristics

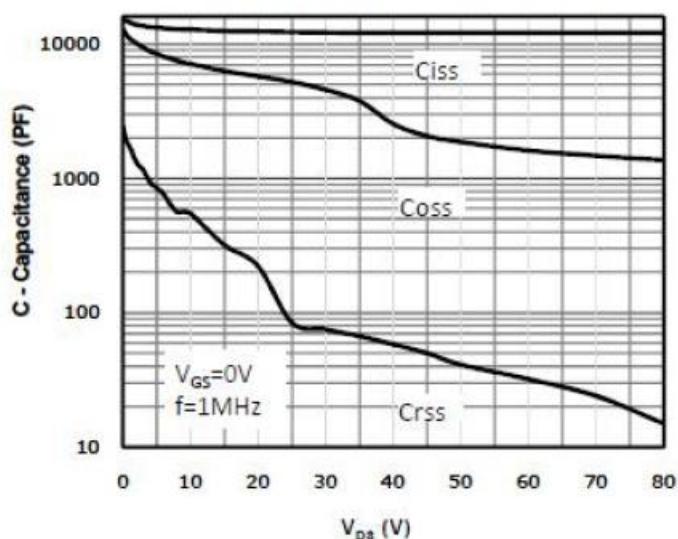
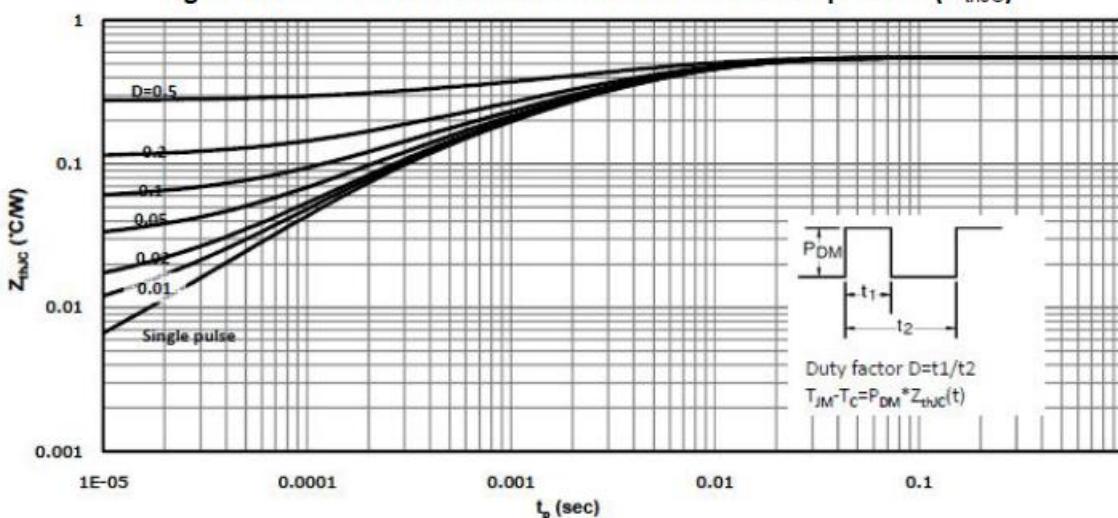


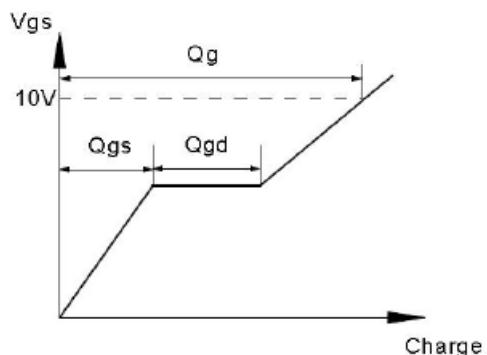
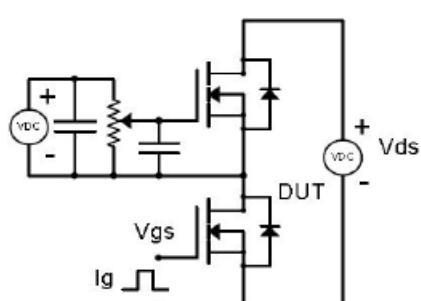
Figure 10. Normalized Maximum Transient Thermal Impedance (R_{thJC})



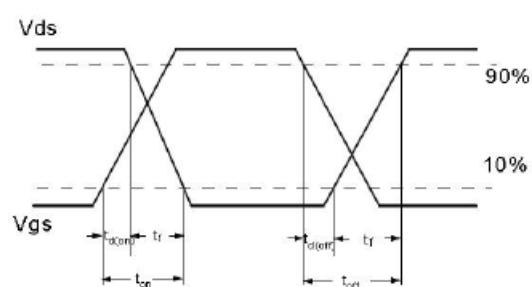
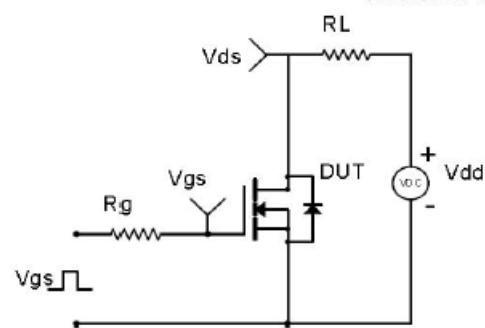


Test Circuit & Waveform

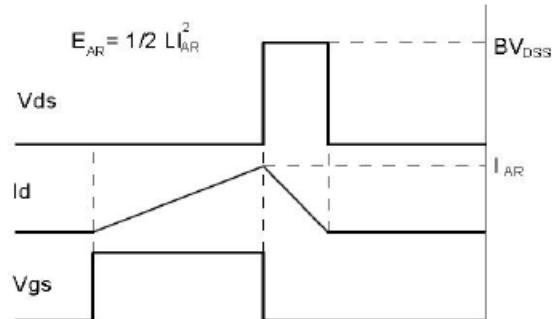
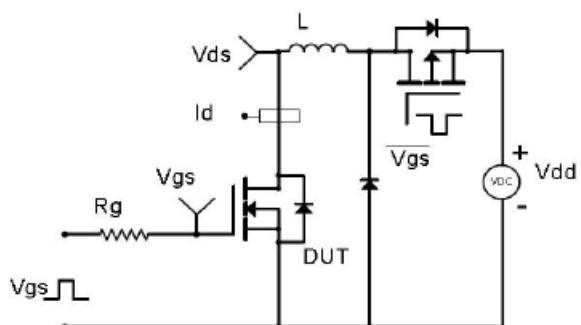
Gate Charge Test Circuit & Waveform



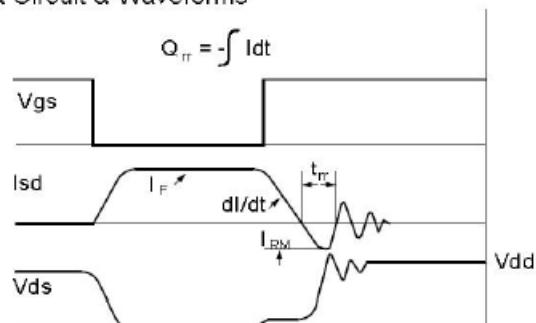
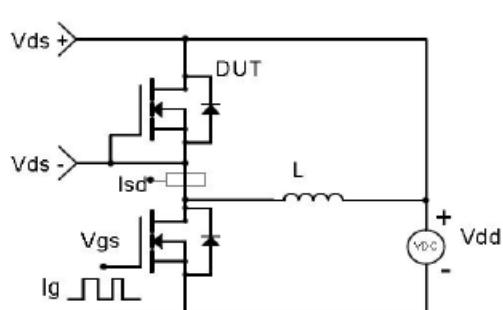
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms





HUASHUO
SEMICONDUCTOR

HSBL020N08

Package Outline: TOLL

